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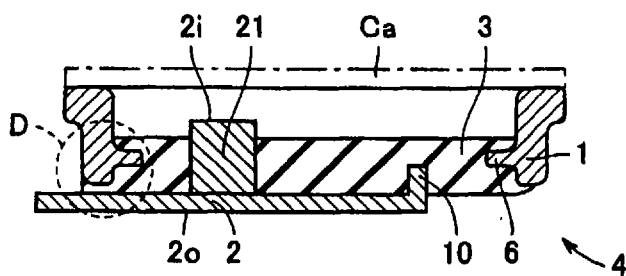
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(54) Title: THIN METAL PACKAGE AND MANUFACTURING METHOD THEREOF



(57) Abstract: A surface mounting package includes a metal base (1) with a lower surface having a through hole, a metal lead (2) arranged to be inserted into the through hole, an insulating material (3) arranged at an internal space of the metal base (1), a cap covering the metal base (1) as a lid, and an electronic part component arranged at a surface (2i) of the metal lead (2) that is positioned at the internal space of the metal base (1). The internal space is held at an air-tight atmosphere. The metal lead (2) forms a surface for attaching the metal base (1) to a mounting board. An insulation distance between the metal lead (2) and the metal base (1)

is at least 0.05 mm and at most 0.3 mm.